



PATENT APPLICATION

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q62153

Takuo FUNAYA, et al.

Appln. No.: 09/730,849

Group Art Unit: 2818

Confirmation No.: 9306

Examiner: D. Nhu

Filed: December 07, 2000

For: ELECTRONIC DEVICE ASSEMBLY AND A METHOD OF CONNECTING
ELECTRONIC DEVICES CONSTITUTING THE SAME

**INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. §§ 1.97 and 1.98**

Commissioner for Patents
Washington, D.C. 20231

Sir:

In accordance with the duty of disclosure under 37 C.F.R. § 1.56, Applicant hereby notifies the U.S. Patent and Trademark Office of the documents which are listed on the attached PTO/SB/08 A & B (modified) form and/or listed herein and which the Examiner may deem material to patentability of the claims of the above-identified application.

1. Japanese Unexamined Patent Publication No. 10-135404, published May 22, 1998.
2. Japanese Unexamined Patent Publication No. 63-142663, published June 15, 1988.
3. Japanese Unexamined Patent Publication No. 2000-243904, published September 8, 2000.
4. Japanese Unexamined Patent Publication No. 2000-82723, published March 21, 2000.

One copy of each of the listed documents is submitted herewith.

The present Information Disclosure Statement is being filed: (1) No later than three months from the application's filing date for an application other than a continued prosecution

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Information Disclosure Statement

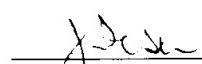
application (CPA) under § 1.53(d); (2) Before the mailing date of the first Office Action on the merits (whichever is later); or (3) Before the mailing date of the first Office Action after filing a request for continued examination (RCE) under § 1.114, and therefore, no Statement under 37 C.F.R. § 1.97(e) or fee under 37 C.F.R. § 1.17(p) is required.

The present Information Disclosure Statement is being filed thirty days or fewer from the communication from a foreign patent office and a Statement Under 37 C.F.R. § 1.704(d) is attached.

In compliance with the concise explanation requirement under 37 C.F.R. § 1.98(a)(3) for foreign language documents, Applicant encloses herewith a copy of a Japanese Office Action dated February 19, 2003 with an English translation of the pertinent portions thereof which cites such documents and indicates the degree of relevance found by the foreign patent office.

The submission of the listed documents is not intended as an admission that any such document constitutes prior art against the claims of the present application. Applicant does not waive any right to take any action that would be appropriate to antedate or otherwise remove any listed document as a competent reference against the claims of the present application.

Respectfully submitted,


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PATENT TRADEMARK OFFICE
Date: March 19, 2003

Note (For a list of the cited literature, see the List of Cited Literature.)

- Claims 1–6
- Cited Literature 1
- Remarks

Compared to the invention described in Cited Example 1 (cf. in particular Figures 1–3 and paragraphs (0018)–(0030)), the invention of the present application differs in that “multiple electronic devices of multiple types are connected to a single electronic device”, while in the invention described in Cited Literature 1, a single different semiconductor chip is connected to a single semiconductor chip.

However, the method of forming aggregates of electronic devices by joining multiple types of electronic devices to one electronic device is a well-known method. In fact, making the modification to have multiple types of electronic devices connected to the single semiconductor chip described in Cited Literature 1 is something that could be easily accomplished by a person skilled in the art.

- Claims 1, 3–5
- Cited Literature 2
- Remarks

See in particular Figures 1–6 and the description of the embodiment examples of Cited Example 2. The situation is the same as with the comparison to Cited Example 1.

No reasons for rejection have been discovered at present for inventions as per claims other than the claims indicated in this notice of reasons for rejection. If any reasons for rejection are newly discovered, a notice of reasons for rejection will be issued.

List of Cited Literature

1. Japanese Unexamined Patent Application Publication H10-135404
2. Japanese Unexamined Patent Application Publication S63-142663

Record of Prior Art Literature Search Results

- Fields searched IPC 7th Edition H10L 25/00–25/18
- Prior art literature Japanese Unexamined Patent Application Publication 2000-243904
 Japanese Unexamined Patent Application Publication 2000-082723

This Record of Prior Art Literature Search Results does not constitute a reason for rejection.



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STATEMENT UNDER 37 C.F.R. § 1.704(d)

Commissioner for Patents
Washington, D.C. 20231

Sir:

The undersigned hereby states, upon information and belief:

That each item of information contained in the Information Disclosure Statement filed concurrently herewith was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned, that the communication was not received by any individual designated in 37 C.F.R. § 1.56(c) more than thirty days prior to the filing of said Information Disclosure Statement.

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